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- Available in 5-V, 4.85-V, and 3.3-V
 Fixed-Output and Adjustable Versions
- Very Low-Dropout Voltage . . . Maximum of 32 mV at I_O = 100 mA (TPS7150)
- Very Low Quiescent Current Independent of Load . . . 285 μA Typ
- Extremely Low Sleep-State Current 0.5 μA Max
- 2% Tolerance Over Specified Conditions For Fixed-Output Versions
- Output Current Range of 0 mA to 500 mA
- TSSOP Package Option Offers Reduced Component Height for Space-Critical Applications
- Power-Good (PG) Status Output

description

The TPS71xx integrated circuits are a family of micropower low-dropout (LDO) voltage regulators. An order of magnitude reduction in dropout voltage and quiescent current over conventional LDO performance is achieved by replacing the typical pnp pass transistor with a PMOS device.

NC – No internal connection † SENSE – Fixed voltage options only (TPS7133, TPS7148, and TPS7150) ‡ FB – Adjustable version only (TPS7101)

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (maximum of 32 mV at an output current of 100 mA for the TPS7150) and is directly proportional to the output current (see Figure 1). Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and remains independent of output loading (typically 285 μ A over the full range of output current, 0 mA to 500 mA). These two key specifications yield a significant improvement in operating life for battery-powered systems. The LDO family also features a sleep mode; applying a TTL high signal to EN (enable) shuts down the regulator, reducing the quiescent current to 0.5 μ A maximum at T₁ = 25°C.



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D	OR P (TOP	PACKA VIEW)	GE
GND EN IN IN	1 2 3 4	8 7 6 5] PG] SENSE†/FB‡] OUT] OUT
F	PW PA (TOP	CKAG VIEW)	E
GND		20	I PG
		19	
GND		18	
NC		17] FB‡
NC	5	16	Тис
ΕN	6	15	SENSE [†]
NC	7	14	Ουτ
IN	8	13] Ουτ
IN	9	12] NC
IN	10	11	NC

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description (continued)



Power good (PG) reports low output voltage and can be used to implement a power-on reset or a low-battery indicator.

The TPS71xx is offered in 3.3-V, 4.85-V, and 5-V fixed-voltage versions and in an adjustable version (programmable over the range of 1.2 V to 9.75 V). Output voltage tolerance is specified as a maximum of 2% over line, load, and temperature ranges (3% for adjustable version). The TPS71xx family is available in PDIP (8 pin), SO (8 pin), and TSSOP (20-pin) packages. The TSSOP has a maximum height of 1,2 mm.

т.	OUTPUT VOLTAGE (V)		PAG	CHIP FORM			
IJ	MIN	TYP	МАХ	SMALL OUTLINE (D)	PLASTIC DIP (P)	TSSOP (PW)	(Y)
	4.9	5	5.1	TPS7150QD	TPS7150QP	TPS7150QPW	TPS7150Y
	4.75	4.85	4.95	TPS7148QD	TPS7148QP	TPS7148QPW	TPS7148Y
-40°C to 125°C	3.23	3.3	3.37	TPS7133QD	TPS7133QP	TPS7133QPW	TPS7133Y
	Ac 1.2	ljustable [†] V to 9.75	V	TPS7101QD	TPS7101QP	TPS7101QPW	TPS7101Y

AVAILABLE OPTIONS

[†]The D and PW packages are available taped and reeled. Add R suffix to device type (e.g., TPS7150QDR). The TPS7101Q is programmable using an external resistor divider (see application information). The chip form is tested at 25°C.





 TPS7133, TPS7148, TPS7150 (fixed-voltage options)
 Capacitor selection is nontrivial. See application information section for details.

Figure 2. Typical Application Configuration

TPS71xx chip information

These chips, when properly assembled, display characteristics similar to the TPS71xxQ. Thermal compression or ultrasonic bonding may be used on the doped aluminum bonding pads. The chips may be mounted with conductive epoxy or a gold-silicon preform.





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functional block diagram



[†] Switch positions are shown with \overline{EN} low (active).

[‡] For most applications, SENSE should be externally connected to OUT as close as possible to the device. For other implementations, refer to SENSE-pin connection discussion in Applications Information section.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)§

Input voltage range¶, V _I , PG, SENSE, EN	
Output current, I _O	2 A
Continuous total power dissipation	See Dissipation Rating Tables 1 and 2
Operating virtual junction temperature range, T _J	
Storage temperature range, T _{stg}	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds .	

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

 \P All voltage values are with respect to network terminal ground.

DISSIPATION RATING TABLE 1 – FREE-AIR TEMPERATURE (see Figure 3)#

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	145 mW
Р	1175 mW	9.4 mW/°C	752 mW	235 mW
PWII	700 mW	5.6 mW/°C	448 mW	140 mW

DISSIPATION RATING TABLE 2 – CASE TEMPERATURE (see Figure 4)[#]

PACKAGE	T _C ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _C = 25°C	T _C = 70°C POWER RATING	T _C = 125°C POWER RATING
D	2188 mW	17.5 mW/°C	1400 mW	438 mW
Р	2738 mW	21.9 mW/°C	1752 mW	548 mW
PW	4025 mW	32.2 mW/°C	2576 mW	805 mW

[#] Dissipation rating tables and figures are provided for maintenance of junction temperature at or below absolute maximum temperature of 150°C. For guidelines on maintaining junction temperature within recommended operating range, see the Thermal Information section.

Il Refer to Thermal Information section for detailed power dissipation considerations when using the TSSOP packages.



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[†] Dissipation rating tables and figures are provided for maintenance of junction temperature at or below absolute maximum temperature of 150°C. For guidelines on maintaining junction temperature within recommended operating range, see the Thermal Information section.

recommended operating conditions

			MIN	MAX	UNIT
	TPS7101Q		2.5	10	
	TPS7133Q	3	3.77	10	V
input voltage, v +	TPS7148Q		5.2	10	v
	TPS7150Q	Ę	5.33	10	
High-level input voltage at EN, VIH			2		V
Low-level input voltage at EN, VIL				0.5	V
Output current range, IO			0	500	mA
Operating virtual junction temperature range, T_J		-	-40	125	°C

[‡] Minimum input voltage defined in the recommended operating conditions is the maximum specified output voltage plus dropout voltage at the maximum specified load range. Since dropout voltage is a function of output current, the usable range can be extended for lighter loads. To calculate the minimum input voltage for your maximum output current, use the following equation: V_{I(min)} = V_{O(max)} + V_{DO(max load)} Because the TPS7101 is programmable, r_{DS(on)} should be used to calculate V_{DO} before applying the above equation. The equation for calculating V_{DO} from r_{DS(on)} is given in Note 2 in the electrical characteristics table. The minimum value of 2.5 V is the absolute lower limit for the recommended input voltage range for the TPS7101.



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electrical characteristics at I_O = 10 mA, \overline{EN} = 0 V, C_O = 4.7 μ F/CSR[†] = 1 Ω , SENSE/FB shorted to OUT (unless otherwise noted)

PARAMETER	TEST CON	DITIONS [‡]	ТJ	TPS710 TPS714	1Q, TPS 8Q, TPS	7133Q 7150Q	UNIT
				MIN	TYP	MAX	
Ground current (active mode)	$\overline{EN} \le 0.5 \text{ V},$	VI = VO + 1 V,	25°C		285	350	۵
Ground current (active mode)	$0 \text{ mA} \leq I_O \leq 500 \text{ mA}$		-40°C to 125°C			460	μΛ
Input current (standby mode)		271/21/2 = 101/2	25°C			0.5	
input current (standby mode)	EN = V	$2.7 \forall \leq \forall \leq 10 \forall$	-40°C to 125°C			2	μΛ
		$V_{1} = 10 V_{1}$	25°C		1.2	2	٨
	vO = 0,	v] = 10 v	-40°C to 125°C			2	Υ.
Pass-element leakage current in standby		27/////////////////////////////////////	25°C			0.5	
mode	$\exists N = V ,$	$2.7 \vee \leq \vee \leq 10 \vee$	-40° C to 125° C			1	μА
PG leakage current	Normal operation	VPG = 10 V	25°C		0.02	0.5	μA
	Normai operation,		-40° C to 125° C			0.5	
Output voltage temperature coefficient			-40° C to 125° C		61	75	ppm/°C
Thermal shutdown junction temperature					165		°C
EN logic bigb (stondby mode)	$2.5 V \le V_I \le 6 V$		40°C to 125°C	2			V
EN logic high (standby hode)	$6~V \leq V_{I} \leq 10~V$		-40 C 10 125 C	2.7			v
EN logic low (active mode)	271/21/2 = 101/		25°C			0.5	V
EN logic low (active mode)	$2.7 \forall \leq \forall \leq 10 \forall$		-40°C to 125°C			0.5	v
EN hysteresis voltage			25°C		50		mV
	$0 V \leq V \leq 10 V$	0 V < V < 10 V	25°C	-0.5		0.5	
EN Input current	$0 V \leq V \leq 10 V$	$0 v \leq v \leq 10 v$	-40° C to 125° C	-0.5		0.5	μΑ
Minimum V/, for active page element			25°C		2.05	2.5	V
Ninimum v for active pass element			-40° C to 125° C			2.5	v
			25°C		1.06	1.5	V
	IPG = 300 μA IPG = 300 μA		-40°C to 125°C			1.9	v

[†]CSR (compensation series resistance) refers to the total series resistance, including the equivalent series resistance (ESR) of the capacitor, any series resistance added externally, and PWB trace resistance to CO.

[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.



TPS7101 electrical characteristics at I_O = 10 mA, V_I = 3.5 V, \overline{EN} = 0 V, C_O = 4.7 μ F/CSR[†] = 1 Ω , FB shorted to OUT at device leads (unless otherwise noted)

			_	Т	PS71010	2	
PARAMETER	TEST CO	TEST CONDITIONS+		MIN	TYP	MAX	UNIT
Potoronoo voltago (moosurod at ER	V _I = 3.5 V,	I _O = 10 mA	25°C		1.178		V
with OUT connected to FB)	2.5 V \leq V _I \leq 10 V, See Note 1	5 mA \leq I _O \leq 500 mA,	-40°C to 125°C	1.143		1.213	V
Reference voltage temperature coefficient			-40°C to 125°C		61	75	ppm/°C
	V _I = 2.4 V,	$E0 = 0 \leq 10 \leq 150 = 0$	25°C		0.7	1	
		$50 \ \mu A \le 10 \le 150 \ m A$	-40°C to 125°C			1	
	$\lambda = 2.4 \lambda$	$150 \text{ mA} \le I_{O} \le 500$	25°C		0.83	1.3	
Pass-element series resistance	$v_{\parallel} = 2.4 v_{,}$	mA	-40°C to 125°C			1.3	0
(see Note 2)	$y_{1} = 2.0 y_{1}$		25°C		0.52	0.85	52
	v] = 2.9 v,	$50 \ \mu\text{A} \le 10 \le 500 \ \text{mA}$	-40°C to 125°C			0.85	
	V _I = 3.9 V,	$50 \ \mu A \le I_O \le 500 \ mA$	25°C		0.32		
	V _I = 5.9 V,	$50 \ \mu A \leq I_O \leq 500 \ mA$	25°C		0.23		
	V _I = 2.5 V to 10 V, See Note 1	50 μ A \leq I _O \leq 500 mA,	25°C			18	mV
Input regulation			-40°C to 125°C			25	
	$I_{O} = 5 \text{ mA to } 500 \text{ mA},$	2.5 V ≤ V _I ≤ 10 V,	25°C			14	mV
Output regulation	See Note 1	•	-40°C to 125°C			25	
Output regulation	$I_{O} = 50 \ \mu A$ to 500 mA, See Note 1	$2.5 \text{ V} \leq \text{V}_{I} \leq 10 \text{ V},$	25°C			22	
			-40°C to 125°C			54	IIIV
		10 - 50 4	25°C	48	59		
Pipple rejection	f - 120 Hz	$IO = 50 \mu A$	-40°C to 125°C	44			dD
	1 = 120 HZ	IO = 500 mA,	25°C	45	54		uБ
		See Note 1	-40°C to 125°C	44			
Output noise-spectral density	f = 120 Hz		25°C		2		$\mu V/\sqrt{Hz}$
		C _O = 4.7 μF	25°C		95		
Output noise voltage	10 Hz ≤ f ≤ 100 kHz, CSPt = 1 0	C _O = 10 μF	25°C		89		μVrms
	00101 = 1 22	C _O = 100 μF	25°C		74		
PG trip-threshold voltage§	VFB voltage decreasing	from above V _{PG}	-40°C to 125°C	1.101		1.145	V
PG hysteresis voltage§	Measured at VFB		25°C		12		mV
	L 400 A	<u> </u>	25°C		0.1	0.4	
PG output low voltage ³	IPG = 400 μA,	$V_{I} = 2.13 V$	-40°C to 125°C			0.4	V
			25°C	-10	0.1	10	
FB input current			-40°C to 125°C	-20		20	nA

[†]CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.

[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

§ Output voltage programmed to 2.5 V with closed-loop configuration (see application information).

NOTES: 1. When V_I < 2.9 V and I_O > 150 mA simultaneously, pass element r_{DS(on)} increases (see Figure 27) to a point such that the resulting dropout voltage prevents the regulator from maintaining the specified tolerance range.

2. To calculate dropout voltage, use equation:

 $V_{DO} = I_O \cdot r_{DS(on)}$

 $r_{DS(on)}$ is a function of both output current and input voltage. The parametric table lists $r_{DS(on)}$ for V_I = 2.4 V, 2.9 V, 3.9 V, and 5.9 V, which corresponds to dropout conditions for programmed output voltages of 2.5 V, 3 V, 4 V, and 6 V, respectively. For other programmed values, refer to Figure 26.



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TPS7133 electrical characteristics at I_O = 10 mA, V_I = 4.3 V, \overline{EN} = 0 V, C_O = 4.7 μ F/CSR[†] = 1 Ω , SENSE shorted to OUT (unless otherwise noted)

	TEST CONDITIONS		-	TF	TPS7133Q			
PARAMETER	TEST CON	DITIONS+	l IJ	MIN	TYP	MAX	UNIT	
Output veltoge	V _I = 4.3 V,	I _O = 10 mA	25°C		3.3		V	
Output voltage	$4.3~V \leq V_{I} \leq 10~V,$	$5 \text{ mA} \le I_O \le 500 \text{ mA}$	-40°C to 125°C	3.23		3.37	v	
	la 10 mA	Vi. 2.22.V	25°C		4.5	7		
	IO = 10 MA,	V = 3.23 V	-40°C to 125°C			8		
Dranauturahana	$l_{0} = 100 \text{ m}$	Vi – 2 22 V	25°C		47	60	m\/	
Dropout voltage	IO = 100 IIIA,	v] = 3.23 v	-40°C to 125°C			80	IIIV	
	$l_{0} = 500 \text{ m}$	1/1 = 2.22	25°C		235	300		
	IO = 500 mA,	v = 3.23 v	-40°C to 125°C			400		
Bass element series resistance	(3.23 V – V _O)/I _O ,	VI = 3.23 V,	25°C		0.47	0.6	0	
Pass-element series resistance	I _O = 500 mA		-40°C to 125°C			0.8	52	
	V _I = 4.3 V to 10 V,	$50 \ \mu A \le I_O \le 500 \ mA$	25°C			20	m\/	
input regulation vi =			-40°C to 125°C			27	IIIV	
	I_{O} = 5 mA to 500 mA,	$4.3 \text{ V} \leq \text{V}_I \leq 10 \text{ V}$	25°C		21	38	m۷	
			-40°C to 125°C			75		
Output regulation		$4.3 \text{ V} \leq \text{V}_{I} \leq 10 \text{ V}$	25°C		30	60		
	$10 = 30 \mu A 10 300 \text{mA},$		-40°C to 125°C			120	IIIV	
		L 50 A	25°C	43	54			
Pipple rejection	f = 120 Hz	ΙΟ = 50 μΑ	-40°C to 125°C	40			dB	
	1 = 120112	$l_{0} = 500 \text{ mA}$	25°C	39	49		uв	
		10 = 300 mA	-40°C to 125°C	36				
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√Hz	
		C _O = 4.7 μF	25°C		274			
Output noise voltage	$10 \text{ Hz} \le f \le 100 \text{ kHz},$	C _O = 10 μF	25°C		228		μVrms	
	001(1 = 1 12	C _O = 100 μF	25°C		159			
PG trip-threshold voltage	VO voltage decreasing	from above V _{PG}	-40°C to 125°C	2.868		3	V	
PG hysteresis voltage			25°C		35		mV	
	4		25°C		0.22	0.4	Ň	
PG output low voltage	PG = 1 mA,	vj = 2.8 v	-40°C to 125°C			0.4	V	

† CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to CO.

[‡]Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.



TPS7148 electrical characteristics at $I_0 = 10 \text{ mA}$, $V_1 = 5.85 \text{ V}$, $\overline{EN} = 0 \text{ V}$, $C_0 = 4.7 \mu \text{F/CSR}^{\dagger} = 1 \Omega$, SENSE shorted to OUT (unless otherwise noted)

DADAMETED	TEST CON		т.	TF	PS71480	2	
PARAMETER	TEST CON	DITIONS+	IJ	MIN	TYP	MAX	UNIT
Output voltage	V _I = 5.85 V,	I _O = 10 mA	25°C		4.85		V
Output voltage	5.85 V \leq V _I \leq 10 V,	$5 \text{ mA} \le I_{O} \le 500 \text{ mA}$	-40°C to 125°C	4.75		4.95	v
	10 - 10		25°C		2.9	6	
	IO = 10 MA,	v] = 4.75 v	-40°C to 125°C			8	
Dranauturaltage	$l_{0} = 100 \text{ mA}$	$V_{1} = 4.75 V_{1}$	25°C		30	37	m\/
Dropout voltage	IO = 100 IIIA,	v] = 4.75 v	-40°C to 125°C			54	IIIV
	$l_{0} = 500 \text{ mA}$	\/ 4 75 \/	25°C		150	180	
	IO = 500 IIIA,	v] = 4.75 v	-40° C to 125° C			250	
Page element estice registeres	(4.75 V – V _O)/I _O ,	V _I = 4.75 V,	25°C		0.32	0.35	0
Pass-element series resistance	I _O = 500 mA		-40° C to 125° C			0.52	52
	$V_{1} = 5.85 V_{1} = 10 V_{1}$	$50 \ \mu A \le I_{O} \le 500 \ mA$	25°C			27	m\/
input regulation	$v_{\parallel} = 5.65 v t0 10 v,$		-40°C to 125°C			37	IIIV
	I _O = 5 mA to 500 mA,	$5.85~V \le V_I \le 10~V$	25°C		12	42	mV
			-40° C to 125° C			80	
		$5.85~V \le V_I \le 10~V$	25°C		42	60	
	$10 = 30 \mu \text{A to } 300 \text{mA},$		-40°C to 125°C			130	IIIV
		L 50 A	25°C	42	53		
Pipple rejection	f – 120 H 7	$IO = 50 \mu A$	-40° C to 125° C	39			dB
	1 = 120112	$l_{0} = 500 \text{ mA}$	25°C	39	50		uв
		IO = 300 IIIA	-40° C to 125° C	35			
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√Hz
		C _O = 4.7 μF	25°C		410		
Output noise voltage	$10 \text{ Hz} \le f \le 100 \text{ kHz},$	C _O = 10 μF	25°C		328		μVrms
		C _O = 100 μF	25°C		212		
PG trip-threshold voltage	VO voltage decreasing	from above V _{PG}	-40°C to 125°C	4.5		4.7	V
PG hysteresis voltage			25°C		50		mV
		N/ //0.)/	25°C		0.2	0.4	
PG output low voltage	IPG = 1.2 mA,	vj = 4.12 v	-40°C to 125°C			0.4	V

[†]CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.

[‡] Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.



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TPS7150 electrical characteristics at I_O = 10 mA, V_I = 6 V, \overline{EN} = 0 V, C_O = 4.7 μ F/CSR[†] = 1 Ω , SENSE shorted to OUT (unless otherwise noted)

	7507.001	TEST CONDITIONS		TF	PS71500	ג	
PARAMETER	TEST CON	DITIONS+	IJ	MIN	TYP	MAX	UNIT
Output veltage	V _I = 6 V,	I _O = 10 mA	25°C		5		V
Output voltage	$6 \text{ V} \leq \text{V}_{I} \leq 10 \text{ V},$	$5 \text{ mA} \le I_O \le 500 \text{ mA}$	-40°C to 125°C	4.9		5.1	v
	10 - 10		25°C		2.9	6	
	10 = 10 IIIA,	V = 4.88 V	-40°C to 125°C			8	
Dramautiveliana	$l_{0} = 100 \text{ mA}$	V 4 99 V	25°C		27	32	m\/
Dropout voltage	O = 100 mA,	V = 4.00 V	-40° C to 125° C			47	ШV
	$l_{0} = 500 \text{ mA}$	\/ 4 99 \/	25°C		146	170	
	IO = 500 mA,	v] = 4.00 v	-40° C to 125° C			230	
Base element series resistance	(4.88 V – V _O)/I _O ,	VI = 4.88 V,	25°C		0.29	0.32	0
Fass-element series resistance	I _O = 500 mA		-40°C to 125°C			0.47	52
	$V_{\rm H} = 6 V_{\rm H} to 10 V_{\rm H}$	$50 \ \mu\text{A} \le \text{I}_{O} \le 500 \ \text{mA}$	25°C			25	m\/
input regulation	v = 6 v to 10 v,		-40°C to 125°C			32	ШV
	I _O = 5 mA to 500 mA,	$6 \ V \le V_I \le 10 \ V$	25°C		30	45	mV
Output regulation			-40°C to 125°C			86	
		$6 \ V \leq V_{I} \leq 10 \ V$	25°C		45	65	
	$10 = 30 \mu A 10 300 \text{mA},$		-40°C to 125°C			140	IIIV
		I _O = 50 μA	25°C	45	55		
Ripple rejection	f – 120 Hz		-40°C to 125°C	40			dB
	1 = 120112	$l_{0} = 500 \text{ mA}$	25°C	42	52		uВ
		IQ = 300 IIIA	-40°C to 125°C	36			
Output noise-spectral density	f = 120 Hz		25°C		2		μV/√ Hz
		C _O = 4.7 μF	25°C		430		
Output noise voltage	10 Hz \leq f \leq 100 kHz,	C _O = 10 μF	25°C		345		μVrms
	001(1 = 1 22	C _O = 100 μF	25°C		220		
PG trip-threshold voltage	VO voltage decreasing	from above V _{PG}	-40°C to 125°C	4.55		4.75	V
PG hysteresis voltage			25°C		53		mV
	1. 10	<u> </u>	25°C		0.2	0.4	
PG output low voltage	PG = 1.2 mA,	vj = 4.25 V	-40°C to 125°C			0.4	V

† CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to CO.

[‡]Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.



electrical characteristics at I_O = 10 mA, \overline{EN} = 0 V, C_O = 4.7 μ F/CSR[†] = 1 Ω , T_J = 25°C, SENSE/FB shorted to OUT (unless otherwise noted)

PARAMETER	TEST CONDITIONS [‡]	TPS7101Y, TPS7133Y TPS7148Y, TPS7150Y	UNIT
		MIN TYP MAX	
Ground current (active mode)	$\label{eq:eq:expansion} \begin{array}{ c c } \overline{EN} \leq 0.5 \text{ V}, & V_I = V_O + 1 \text{ V}, \\ 0 \text{ mA} \leq I_O \leq 500 \text{ mA} \end{array}$	285	μA
Output current limit	$V_{O} = 0,$ $V_{I} = 10 V$	1.2	A
PG leakage current	Normal operation, $V_{PG} = 10 V$	0.02	μΑ
Thermal shutdown junction temperature		165	°C
EN hysteresis voltage		50	mV
Minimum VI for active pass element		2.05	V
Minimum V _I for valid PG	I _{PG} = 300 μA	1.06	V

DADAMETED	TENT OF		TF			
FARAMETER	TEST CO	INDITIONS+	MIN	TYP	MAX	UNIT
Reference voltage (measured at FB with OUT connected to FB)	VI = 3.5 V,	I _O = 10 mA		1.178		V
	V _I = 2.4 V,	$50 \ \mu A \le I_O \le 150 \ mA$		0.7		
	V _I = 2.4 V,	$150 \text{ mA} \leq I_{O} \leq 500 \text{ mA}$		0.83		
Pass-element series resistance (see Note 2)	V _I = 2.9 V,	$50 \ \mu A \le I_O \le 500 \ mA$		0.52		Ω
	V _I = 3.9 V,	$50 \ \mu A \leq I_O \leq 500 \ mA$		0.32		
	V _I = 5.9 V,	$50 \ \mu A \leq I_O \leq 500 \ mA$		0.23		
Input regulation	V _I = 2.5 V to 10 V, See Note 1	50 μ A \leq I _O \leq 500 mA,			18	mV
	2.5 V \leq V _I \leq 10 V, See Note 1	I_{O} = 5 mA to 500 mA,			14	mV
	2.5 V \leq V _I \leq 10 V, See Note 1	$I_{O} = 50 \ \mu A$ to 500 mA,			22	mV
Ripple rejection	VI = 3.5 V, IO = 50 μA	f = 120 Hz,		59		dB
Output noise-spectral density	VI = 3.5 V,	f = 120 Hz		2		$\mu V/\sqrt{Hz}$
	VI = 3.5 V.	C _O = 4.7 μF		95		
Output noise voltage	10 Hz ≤ f ≤ 100 kHz,	C _O = 10 μF		89		μVrms
	$CSR^{\dagger} = 1 \Omega$	C _O = 100 μF	74			
PG hysteresis voltage§	V _I = 3.5 V,	Measured at V _{FB}		12		mV
PG output low voltage§	V _I = 2.13 V,	IPG = 400 μA		0.1		V
FB input current	V _I = 3.5 V	V _I = 3.5 V		0.1		nA

† CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.

[‡]Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.

§ Output voltage programmed to 2.5 V with closed-loop configuration (see application information).

NOTES: 1. When VI < 2.9 V and IO > 150 mA simultaneously, pass element rDS(on) increases (see Figure 27) to a point such that the resulting dropout voltage prevents the regulator from maintaining the specified tolerance range.

2. To calculate dropout voltage, use equation:

 $V_{DO} = I_O \cdot r_{DS(on)}$

rDS(on) is a function of both output current and input voltage. The parametric table lists rDS(on) for VI = 2.4 V, 2.9 V, 3.9 V, and 5.9 V, which corresponds to dropout conditions for programmed output voltages of 2.5 V, 3 V, 4 V, and 6 V, respectively. For other programmed values, refer to Figure 26.



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electrical characteristics at I_O = 10 mA, \overline{EN} = 0 V, C_O = 4.7 μ F/CSR[†] = 1 Ω , T_J = 25°C, SENSE shorted to OUT (unless otherwise noted) (continued)

DADAMETED	TEST CO	TF	LINUT				
PARAMETER	IESI CO	NDITION5+	MIN	TYP	MAX	UNIT	
Output voltage	V _I = 4.3 V,	I _O = 10 mA		3.3		V	
	V _I = 3.23 V,	l _O = 10 mA		0.02			
Dropout voltage	V _I = 3.23 V,	I _O = 100 mA		47		mV	
	V _I = 3.23 V,	I _O = 500 mA		235			
Pass-element series resistance	$(3.23 V - V_0)/I_0,$ $I_0 = 500 \text{ mA}$	V _I = 3.23 V,		0.47		Ω	
	$4.3 \text{ V} \leq \text{V}_{I} \leq 10 \text{ V},$	$I_{O} = 5 \text{ mA to } 500 \text{ mA}$		21		mV	
	$4.3 \text{ V} \leq \text{V}_{I} \leq 10 \text{ V},$	I_{O} = 50 μ A to 500 mA		30		mV	
Pipple rejection	V _I = 4.3 V, f = 120 Hz	I _O = 50 μA		54		dD	
		I _O = 500 mA		49		uБ	
Output noise-spectral density	V _I = 4.3 V,	f = 120 Hz		2		μV/√Hz	
	VI = 4.3 V.	C _O = 4.7 μF		274			
Output noise voltage	10 Hz ≤ f ≤ 100 kHz,	C _O = 10 μF	228 159			μVrms	
	$CSRT = 1 \Omega$	C _O = 100 μF					
PG hysteresis voltage	V _I = 4.3 V			35		mV	
PG output low voltage	V _I = 2.8 V,	I _{PG} = 1 mA		0.22		V	

DADAMETED	TEST CO	NDITIONS	TF				
PARAMETER	IESI CO	NDITION5+	MIN	TYP	MAX	UNIT	
Output voltage	V _I = 5.85 V,	l _O = 10 mA		4.85		V	
	V _I = 4.75 V,	l _O = 10 mA		0.08			
Dropout voltage	V _I = 4.75 V,	I _O = 100 mA		30		mV	
	V _I = 4.75 V,	I _O = 500 mA		150			
Pass-element series resistance	(4.75 V – V _O)/I _O , I _O = 500 mA	V _I = 4.75 V,		0.32		Ω	
	5.85 V \leq V _I \leq 10 V,	IO = 5 mA to 500 mA		12		mV	
	5.85 V \leq V _I \leq 10 V,	I_{O} = 50 μ A to 500 mA		42		mV	
Pipple rejection	VI = 5.85 V,	IO = 50 μA	53 50			dB	
	f = 120 Hz	I _O = 500 mA			uв		
Output noise-spectral density	V _I = 5.85 V,	f = 120 Hz	2			μV/√Hz	
	Vi = 5.85 V,	C _O = 4.7 μF	410				
Output noise voltage	10 Hz ≤ f ≤ 100 kHz,	C _O = 10 μF		328		μVrms	
	$CSRT = 1 \Omega$	C _O = 100 μF	212]	
PG hysteresis voltage	VI = 5.85 V			50		mV	
PG output low voltage	V _I = 4.12 V,	I _{PG} = 1.2 mA		0.2	0.4	V	

† CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to CO.

[‡]Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.



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electrical characteristics at I_O = 10 mA, \overline{EN} = 0 V, C_O = 4.7 μ F/CSR[†] = 1 Ω , T_J = 25°C, SENSE shorted to OUT (unless otherwise noted) (continued)

DADAMETED	TEST		TF				
PARAMETER	TEST CO	DNDITIONS+	MIN	TYP	MAX	UNIT	
Output voltage	VI = 6 V,	l _O = 10 mA		5		V	
	V _I = 4.88 V,	l _O = 10 mA		0.13			
Dropout voltage	V _I = 4.88 V,	l _O = 100 mA		27		mV	
	V _I = 4.88 V,	l _O = 500 μA		146			
Pass-element series resistance	$(4.88 V - V_{O})/I_{O},$ $I_{O} = 500 \text{ mA}$	V _I = 4.88 V,		0.29		Ω	
	$6 \text{ V} \leq \text{V}_{I} \leq 10 \text{ V},$	$I_{O} = 5 \text{ mA to } 500 \text{ mA}$		30		mV	
	$6 \text{ V} \leq \text{V}_{I} \leq 10 \text{ V},$	$I_{O} = 50 \ \mu A$ to 500 mA		45		mV	
Pipple rejection	$V_{I} = 6 V,$	I _O = 50 μA	55			dB	
	f = 120 Hz	I _O = 500 mA		52		uВ	
Output noise-spectral density	V _I = 6 V,	f = 120 Hz		2		μV/√Hz	
	$V_{I} = 6 V_{.}$	C _O = 4.7 μF		430			
Output noise voltage	10 Hz \le f \le 100 kHz,	C _O = 10 μF		345		μVrms	
	$CSRT = 1 \Omega$	C _O = 100 μF	220				
PG hysteresis voltage	VI = 6 V			53		mV	
PG output low voltage	V _I = 4.25 V,	PG = 1.2 mA		0.2		V	

[†]CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to CO.

[‡]Pulse-testing techniques are used to maintain virtual junction temperature as close as possible to ambient temperature; thermal effects must be taken into account separately.



TYPICAL CHARACTERISTICS

Table of Graphs

			FIGURE
		vs Output current	5
lq	Quiescent current	vs Input voltage	6
		vs Free-air temperature	7
VDO	Dropout voltage	vs Output current	8
ΔV_{DO}	Change in dropout voltage	vs Free-air temperature	9
ΔVO	Change in output voltage	vs Free-air temperature	10
Vo	Output voltage	vs Input voltage	11
ΔVO	Change in output voltage	vs Input voltage	12
			13
Va	Output voltage	va Output ourroot	14
۷٥	Oulput voltage	vs Output current	15
			16
			17
	Pipple rejection		18
		vs riequency	19
			20
			21
	Output spectral poise density		22
	Output spectral hoise density	vs riequency	23
			24
^r DS(on)	Pass-element resistance	vs Input voltage	25
R	Divider resistance	vs Free-air temperature	26
II(SENSE)	SENSE pin current	vs Free-air temperature	27
	FB leakage current	vs Free-air temperature	28
V1	Minimum input voltage for active-pass element	vs Free-air temperature	29
v I	Minimum input voltage for valid PG	vs Free-air temperature	30
li(EN)	Input current (EN)	vs Free-air temperature	31
	Output voltage response from Enable (EN)		32
V _{PG}	Power-good (PG) voltage	vs Output voltage	33
CSP	Componentian parian registering	va Output ourroot	34
CSR	Compensation series resistance	vs Output current	35
COD	Componentian aprice registeres		36
CSR	Compensation series resistance	vs Added ceramic capacitance	37
COD	Componentian aprice registeres		38
USK	compensation series resistance		39
COP	Companyation sories resistance		40
		vo Audeu ceramic capacitance	41











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TYPICAL CHARACTERISTICS



R_I = 500 Ω

100 k

1 M











10 M

30

20

10

0

-10

10

= 25°C T۵

= 3.5 V

100

1.1.1.1.00

 $C_0 = 4.7 \ \mu F (CSR = 1 \ \Omega)$

No Input Capacitance

1.1.1.100

1 k

1.1.1.111

Figure 19

10 k

f - Frequency - Hz









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Figure 33







TYPICAL CHARACTERISTICS



 \dagger CSR values below 0.1 Ω are not recommended.



TYPICAL CHARACTERISTICS



[†]Ceramic capacitor





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APPLICATION INFORMATION

The TPS71xx series of low-dropout (LDO) regulators is designed to overcome many of the shortcomings of earlier-generation LDOs, while adding features such as a power-saving shutdown mode and a power-good indicator. The TPS71xx family includes three fixed-output voltage regulators: the TPS7133 (3.3 V), the TPS7148 (4.85 V), and the TPS7150 (5 V). The family also offers an adjustable device, the TPS7101 (adjustable from 1.2 V to 9.75 V).

device operation

The TPS71xx, unlike many other LDOs, features very low quiescent currents that remain virtually constant even with varying loads. Conventional LDO regulators use a pnp-pass element, the base current of which is directly proportional to the load current through the regulator ($I_{\rm B} = I_{\rm C}/\beta$). Close examination of the data sheets reveals that those devices are typically specified under near no-load conditions; actual operating currents are much higher as evidenced by typical quiescent current versus load current curves. The TPS71xx uses a PMOS transistor to pass current; because the gate of the PMOS element is voltage driven, operating currents are low and invariable over the full load range. The TPS71xx specifications reflect actual performance under load.

Another pitfall associated with the pnp-pass element is its tendency to saturate when the device goes into dropout. The resulting drop in β forces an increase in I_B to maintain the load. During power up, this translates to large start-up currents. Systems with limited supply current may fail to start up. In battery-powered systems, it means rapid battery discharge when the voltage decays below the minimum required for regulation. The TPS71xx guiescent current remains low even when the regulator drops out, eliminating both problems.

Included in the TPS71xx family is a 4.85-V regulator, the TPS7148. Designed specifically for 5-V cellular systems, its 4.85-V output, regulated to within \pm 2%, allows for operation within the low-end limit of 5-V systems specified to \pm 5% tolerance; therefore, maximum regulated operating lifetime is obtained from a battery pack before the device drops out, adding crucial talk minutes between charges.

The TPS71xx family also features a shutdown mode that places the output in the high-impedance state (essentially equal to the feedback-divider resistance) and reduces quiescent current to under 2 µA. If the shutdown feature is not used. EN should be tied to ground. Response to an enable transition is guick; regulated output voltage is reestablished in typically 120 µs.

minimum load requirements

The TPS71xx family is stable even at zero load; no minimum load is required for operation.

SENSE-pin connection

The SENSE pin of fixed-output devices must be connected to the regulator output for proper functioning of the regulator. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit (remote sense) to improve performance at that point. Internally, SENSE connects to a high-impedance wide-bandwidth amplifier through a resistor-divider network and noise pickup feeds through to the regulator output. Routing the SENSE connection to minimize/avoid noise pickup is essential. Adding an RC network between SENSE and OUT to filter noise is not recommended because it can cause the regulator to oscillate.

external capacitor requirements

An input capacitor is not required; however, a ceramic bypass capacitor (0.047 pF to 0.1 μ F) improves load transient response and noise rejection if the TPS71xx is located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.



APPLICATION INFORMATION

external capacitor requirements (continued)

As with most LDO regulators, the TPS71xx family requires an output capacitor for stability. A $10-\mu$ F solid-tantalum capacitor connected from the regulator output to ground is sufficient to ensure stability over the full load range (see Figure 43). Adding high-frequency ceramic or film capacitors (such as power-supply bypass capacitors for digital or analog ICs) can cause the regulator to become unstable unless the ESR of the tantalum capacitor is less than 1.2 Ω over temperature. Where component height and/or mounting area is a problem, physically smaller, $10-\mu$ F devices can be screened for ESR. Figures 34 through 41 show the stable regions of operation using different values of output capacitance with various values of ceramic load capacitance.

In applications with little or no high-frequency bypass capacitance (< 0.2μ F), the output capacitance can be reduced to 4.7 μ F, provided ESR is maintained between the values shown in figures 34 through 41. Because minimum capacitor ESR is seldom if ever specified, it may be necessary to add a $0.5-\Omega$ to $1-\Omega$ resistor in series with the capacitor and limit ESR to 1.5Ω maximum.



[†] TPS7133, TPS7148, TPS7150 (fixed-voltage options)

Figure 43. Typical Application Circuit

programming the TPS7101 adjustable LDO regulator

Programming the adjustable regulators is accomplished using an external resistor divider as shown in Figure 44. The equation governing the output voltage is:

$$V_{O} = V_{ref} \cdot \left(1 + \frac{R1}{R2}\right)$$

where

V_{ref} = reference voltage, 1.178 V typ



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APPLICATION INFORMATION

programming the TPS7101 adjustable LDO regulator (continued)

Resistors R1 and R2 should be chosen for approximately 7-µA divider current. A recommended value for R2 is 169 k Ω with R1 adjusted for the desired output voltage. Smaller resistors can be used, but offer no inherent advantage and consume more power. Larger values of R1 and R2 should be avoided as leakage currents at FB introduce an error. Solving equation 1 for R1 yields a more useful equation for choosing the appropriate resistance:

$$R1 = \left(\frac{V_0}{V_{ref}} - 1\right) \cdot R2$$



OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE	R1	R2	UNIT
2.5 V	191	169	kΩ
3.3 V	309	169	kΩ
3.6 V	348	169	kΩ
4 V	402	169	kΩ
5 V	549	169	kΩ
6.4 V	750	169	kΩ



power-good indicator

The TPS71xx features a power-good (PG) output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the PG output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. PG can be used to drive power-on reset circuitry or as a low-battery indicator. PG does not assert itself when the regulated output voltage falls outside the specified 2% tolerance, but instead reports an output voltage low, relative to its nominal regulated value.

regulator protection

The TPS71xx PMOS-pass transistor has a built-in back diode that safely conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS71xx also features internal current limiting and thermal protection. During normal operation, the TPS71xx limits output current to approximately 1 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 165°C, thermal-protection circuitry shuts it down. Once the device has cooled, regulator operation resumes.





17-Mar-2017

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
TPS7101QD	ACTIVE	SOIC	Drawing	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	(3) Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7101Q	Samples
TPS7101QP	ACTIVE	PDIP	Ρ	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7101QP	Samples
TPS7101QPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PT7101	Samples
TPS7101QPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PT7101	Samples
TPS7133QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7133Q	Samples
TPS7133QP	ACTIVE	PDIP	Ρ	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7133QP	Samples
TPS7133QPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7133QP	Samples
TPS7133QPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PT7133	Samples
TPS7148QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7148Q	Samples
TPS7148QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7148Q	Samples
TPS7148QP	ACTIVE	PDIP	Ρ	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7148QP	Samples



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Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TPS7148QPE4	ACTIVE	PDIP	Ρ	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7148QP	Samples
TPS7150QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	7150Q	Samples
TPS7150QP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TPS7150QP	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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PACKAGE OPTION ADDENDUM

17-Mar-2017

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



All dimensions are nomina	l											
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS7101QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS7101QPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS7133QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS7133QPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS7150QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

13-Feb-2016



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS7101QDR	SOIC	D	8	2500	367.0	367.0	35.0
TPS7101QPWR	TSSOP	PW	20	2000	367.0	367.0	38.0
TPS7133QDR	SOIC	D	8	2500	367.0	367.0	38.0
TPS7133QPWR	TSSOP	PW	20	2000	367.0	367.0	38.0
TPS7150QDR	SOIC	D	8	2500	367.0	367.0	38.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



P(R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. β . This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



LAND PATTERN DATA



NOTES: Α. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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